







DISCRIPTION

FEATURES

Multilayer ceramic structure
Closed magnetic circuit
Avoids crosstalk
Excellent solderability
High reliability

OPTIONS

Tape & Reel is Standard (Qty: 4.000 Pcs)
Bulk Packing Available for smaller quantites
Tolerance: M=20%, N=30% is Standard
Tighter Tolerance available (MOQ on request)

APPLICATIONS

VCRs
Mobile Radios
Cordless Telephones
Modems
Global Position Systems
Wirless Communications Equipment
Network Systems
Computer Products

APPROVAL



PHYSICAL CHARACTERISTICS

• Testing: (Equivalents acceptable) Inductance & Q-HP4195A + HP41951

DCR: VOAC-7412; SRF: HP8753C

• Solderability: 90% of the terminal Electrode shall be covered

Preheat: 260°C ± 5°C for 160 second

Solder: H63AA Eutectic Solder Flux Rosin, Dip for 5 sec. ± 1 sec.

• Thermal Shock: Inductance shall be Within ± 5% of initial value and Q shall be within ± 30% of initial value When temperature is -40°C and 85°C for 30 Min. for each 100 cycles

Operating Temperature : -25°C ~ 85°C
Storage Temperature : -40°C ~ 85°C

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	68	nH	see Site 2
Q factor		Q	8		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	1,40	Ω	max.
Self-Res. Freq.		SRF	700	Mhz	min.
Test-Freq.			100	Mhz	
Rated Current		IDC	100	mA	max.
Saturation Current		Isat		mA	typ.

1. This electronic component is meant to be used in general electronic equipment. Before the incorporation SMT Multi-Layer of this component into any equipment with higher and more reliable requirements such as aviation, Ceramic Chip Inductors aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon Part No.: S11001-68N -Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability Customer: functions DRW: Chang CHKD Young MATL: Chu Chi DATE 06.06.2009 APPD: **FINISH** Vienna Pong Sheet 1 from 2



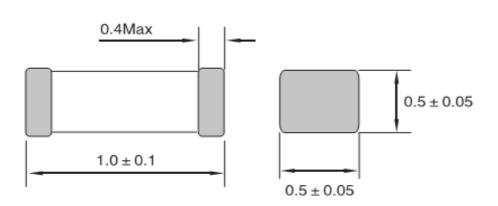






TECHNICAL INFORMATIONS

Dimensions (mm)



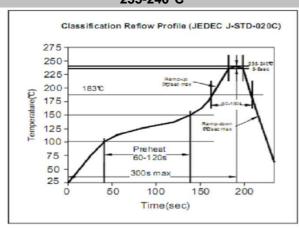
Ordering Information

Serie and Range
S11001-68N

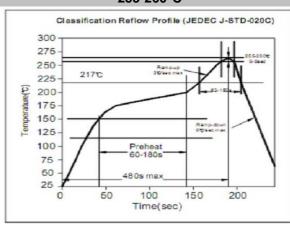
ROHS	Packing	
R	TR	
	ROHS R	

K = 10%	R = ROHS	BU = Bulk Ware
M =20%	N = non ROHS	TR = Tape Reel
N = 30%		

Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



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